

RoHS

Specification

规格书

Customer Name :

客户名称 : _____

Customer P/N :

客户品号 : _____

Factory P/N :

公司品号 : HL-308H203BCN

Sending Date :

送样日期 : _____

Client approval 客户审核			Goozo approval 鸿利国泽审核		
Approval 核准	Audit 确认	Confirmation 制作	Approval 核准	Audit 确认	Confirmation 制作
<input type="checkbox"/> Qualified 接受		<input type="checkbox"/> Disqualified 不接受		DATE: 日期:	

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注:

- 1.此规格书以中英文方式书写,若有冲突以中文版本为准文本.
- 2.此规格书的最终解释权归属江苏鸿利国泽光电科技有限公司



ATTENTION 注意

OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Features

φ3LAMP LED/3m 外形

Low Power Consumption/低功耗

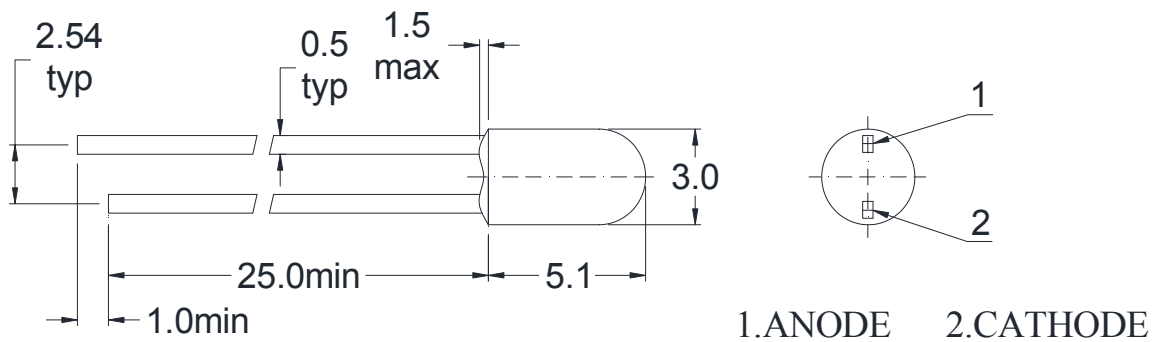
Ideal For Traffic\Backlight Lighting And Indicator

/交通信号、背光、指示用

Description/描述

This devices are made with InGaN /LED

Package Dimensions



Tolerance Grade/公差等级	Dimension Tolerance/尺寸 (Unit:mm)			
	0.5~3	3~6	6~30	30~120
	±0.1	±0.2	±0.3	±0.5
Chip/晶片		Lens Color/胶体颜色		
Material/材质	Emitting Color/ 发光颜色	Water Clear/无色透明		
InGaN	Blue/蓝色			

HL-308H203BCN
■ Absolute Maximum Rating

Item 项目	Symbol 符号	Value 数值	Unit 单位
Forward Current 正向电流	IF	30	mA
Peak Forward Current* 峰值正向电流	IFP	100	mA
Reverse Voltage 反向电压	Vr	5	V
Power Dissipation 功耗	PD	80	mW
Electrostatic discharge 抗静电能力	ESD	4000	V
Operation Temperature 操作温度	Topr	-40~+85	°C
Storage Temperature 储存温度	Tstg	-40~+100	°C
Lead Soldering Temperature* 引脚焊接温度	Tsol	Max. 260°C for 5sec Max.	

*IFP Conditions : Pulse Width≤10msec /IFP 正向峰值电流使用条件 : 脉冲宽度≤10 毫秒

*Tsol Conditions : 1.6mm from the base of the epoxy bulb/Tsol 焊接条件 : 焊接位置离胶体底部 1.6 毫米

■ Typical Optical/ Electrical Characteristics Ta=25°C

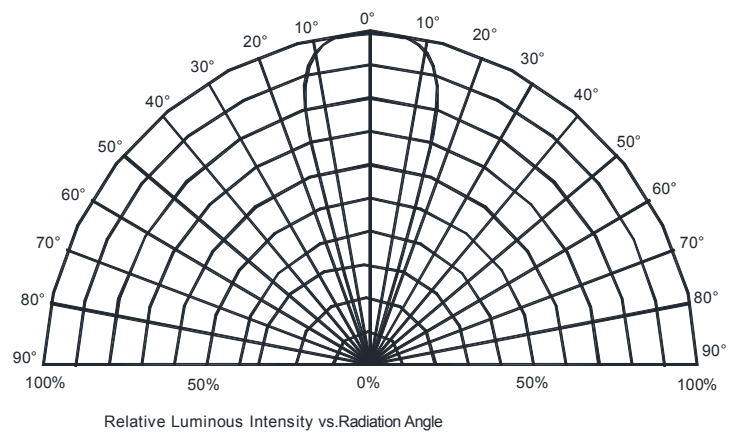
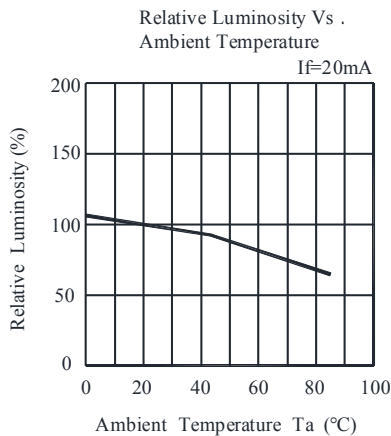
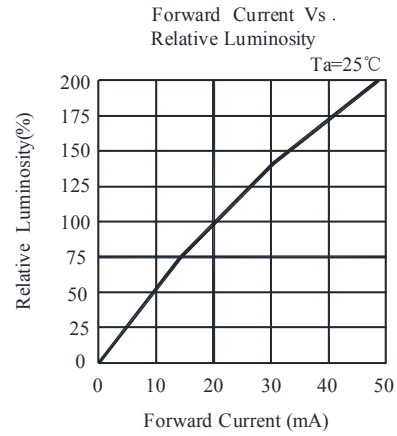
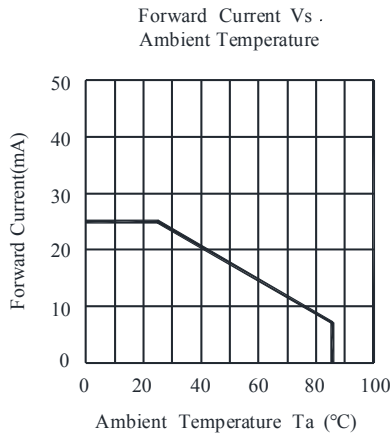
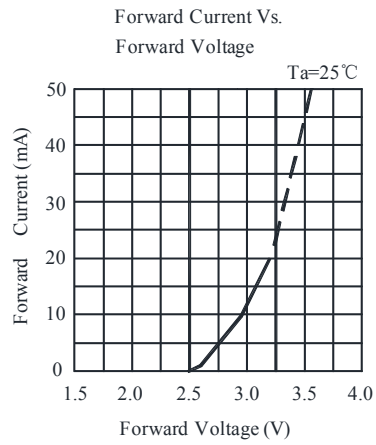
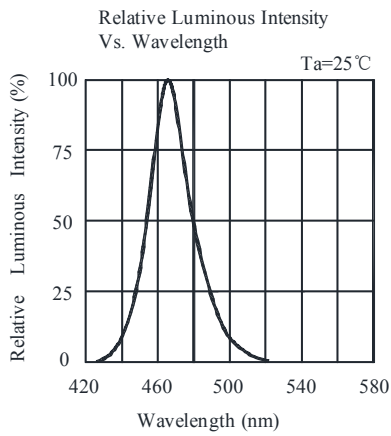
Item/项目	Symbol/符号	Condition/条件	Rank/档次	Min. 最小值	Typ. 典型值	Max. 最大值	Unit 单位
Luminous Intensity/光强	Iv	IF=20mA	V	2230	--	2900	mcd
			W	2900	--	3770	mcd
			X	3770	--	4900	mcd
Forward Voltage/正向电压	VF			2.8	3.2	3.6	V
Viewing Angle/角度	2θ 1/2			--	25	--	deg
Dominant Wavelength/主波长	λ _D				465	--	475
Recommend Forward Current/ 推荐使用正向电流	IF(rec)	--		--	--	20	mA
Reverse Current/反向电流	IR	Vr=5V		--	--	10	uA

Notes/注释:

Tolerance : VF±0.1V , λ_D±2 nm , IV(φV) ±15% , 2θ 1/2±15% , X/Y±0.005.

公差 : 正向电压±0.1V , 主波长±2 nm , 光强 (光通量) ±15% , 角度±15% , X/Y±0.005.

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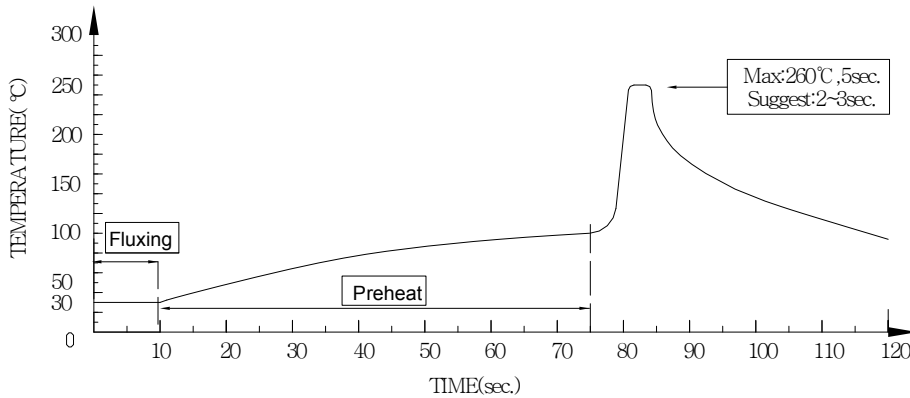


■ Reliability Performance 可靠性

Test Items And Result 测试项目和判定

Test Classification 测试类别	Test Item 测试项目	Test Conditions 测试条件	Test Duration 测试持续时间	Sample Size 样品数量	AC/RE 接受/拒收
Life Test 寿命测试	Room Temperature DC Operating Life Test 室温直流寿命测试	Ta=25°C±5°C , If=20mA	1000 hrs	22 pcs	0/1
Environment Test 环境模拟 实验	Thermal Shock Test 冷热冲击	100°C±5°C 5min ↑↓ -40°C±5°C 5min.	100 cycles	22 pcs	0/1
	Temperature Cycle Test 高低温循环实验	100°C±5°C 30min ↑↓5min -40°C±5°C 30min.	100 cycles	22 pcs	0/1
	High Temperature & High Humidity Test 高温高湿实验	60°C±5°C/90% RH If=5mA	1000 hrs	22 pcs	0/1
	High Temperature Storage 高温储存	Ta=100°C±5°C	1000 hrs	22 pcs	0/1
	Low Temperature Storage 低温储存	Ta=-40°C±5°C	1000 hrs	22 pcs	0/1
Mechanica Test 机械测试	Resistance to Soldering Heat 耐焊接实验	Temp=260°C max T=5sec max	1 times	22 pcs	0/1
	Lead Integrity 引脚折弯实验	Load 2.5N(0.25kgf) 0° ~ 90° ~ 0°	3 times	22 pcs	0/1

■ Dip Soldering/焊接



1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering/在高温焊接过程中，不可有任何外力施加在LED的引脚、环氧上；
2. DIP soldering and hand soldering should not be done more than one time/浸焊、手工焊接次数不可超过1次；
3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temperature/焊接后，在LED温度恢复到室温的过程中，不可受到震动或其它外力的冲击；
4. Avoid rapid cooling during temperature ramp-down process/在LED降温过程中，避免急剧的冷却；
5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs/LED在焊接过程中，应尽可能的降低焊接温度，以减少高温对LED的损伤；

■ IRON Soldering/手动焊接

300°C Within 3 sec., One time only/300°C，3秒，1次；